

X-ray nano-tomography enables high-resolution investigations from micro-bumps to hybrid bonding in advanced packaging

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Application Scientist

NANOTS 2024, Osaka, Japan

A graphic consisting of numerous thin, light blue lines radiating from a central point on the right side of the slide, creating a sunburst or starburst effect.

excillum

The challenge in X-ray inspection and failure analysis

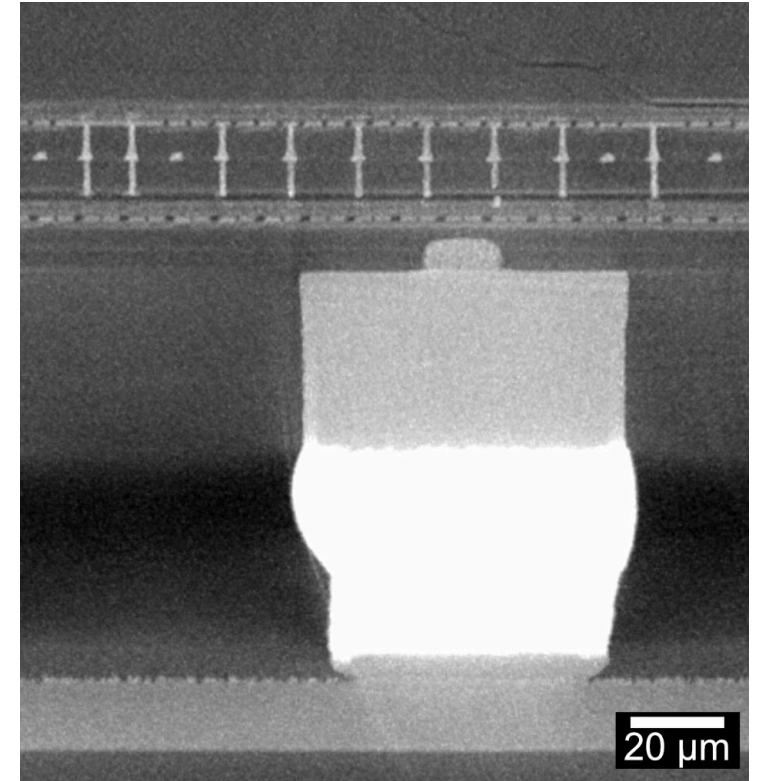
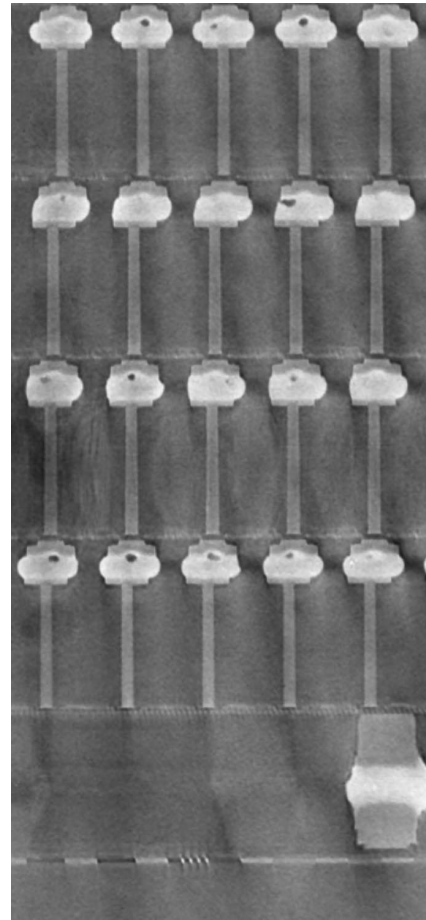
Trends in advanced packaging:

- Smaller and denser interconnects
- Smaller defects
- Buried interconnects
- Tighter tolerances

X-ray CT is becoming increasingly relevant!

Sharper scans – faster ramp up

Improved x-ray inspection to drive development and boost yield



The source for X-ray innovation

Entirely devoted to advanced microfocus and nanofocus X-ray sources

Based in Stockholm, Sweden

Established 2007

80+ colleagues

>40 in R&D

>10 nationalities

Collaborating with leading system integrators

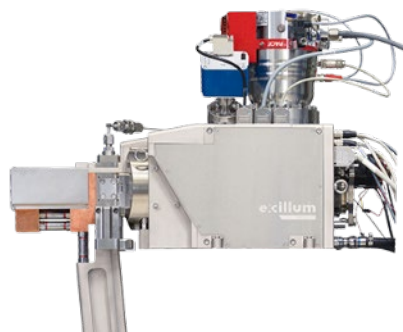


Our technology and product lines

MetalJet

World's brightest microfocus X-ray source

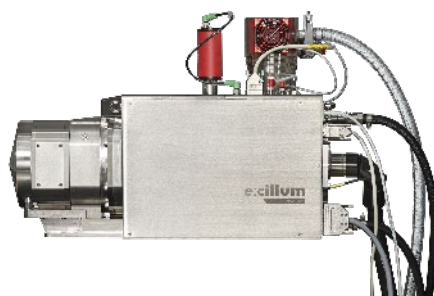
Liquid metal-jet anode and advanced electron beam technologies



NanoTube

World's smallest X-ray nanospot

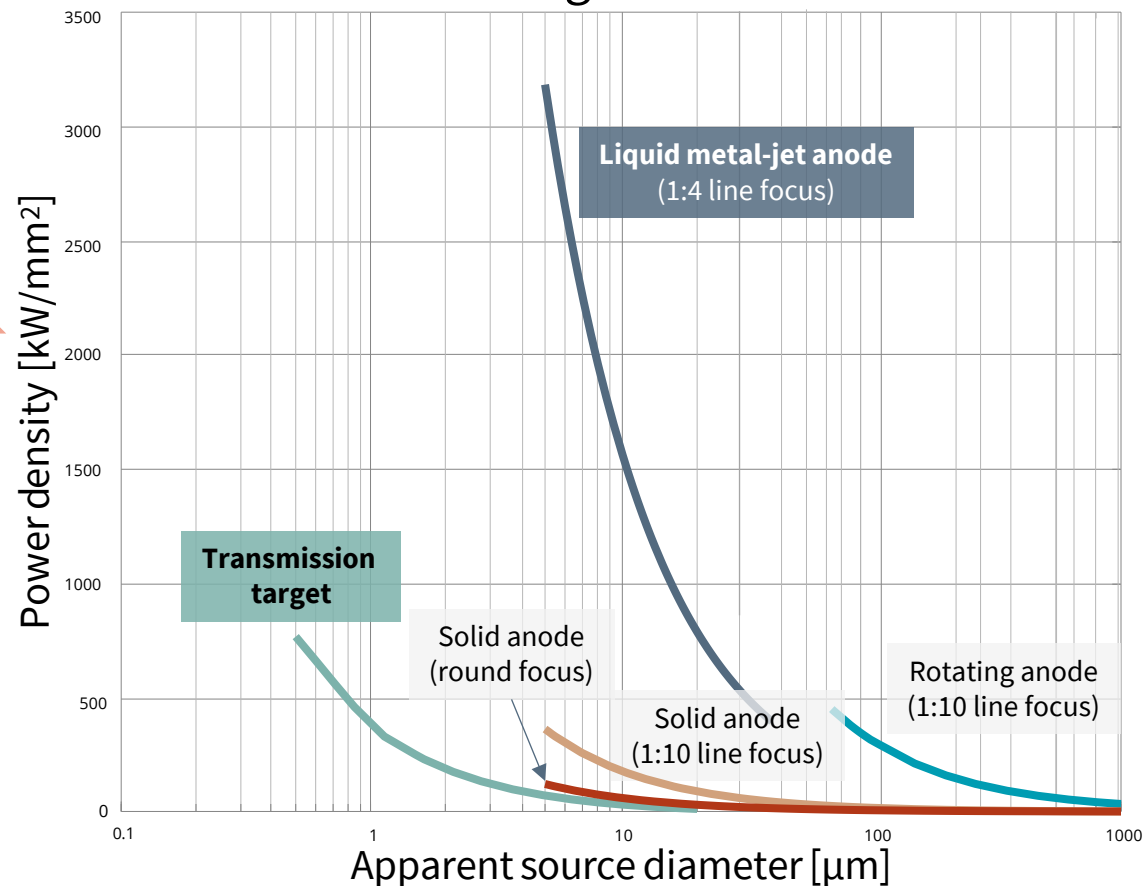
Advanced electron beam technology



Higher inspection speed



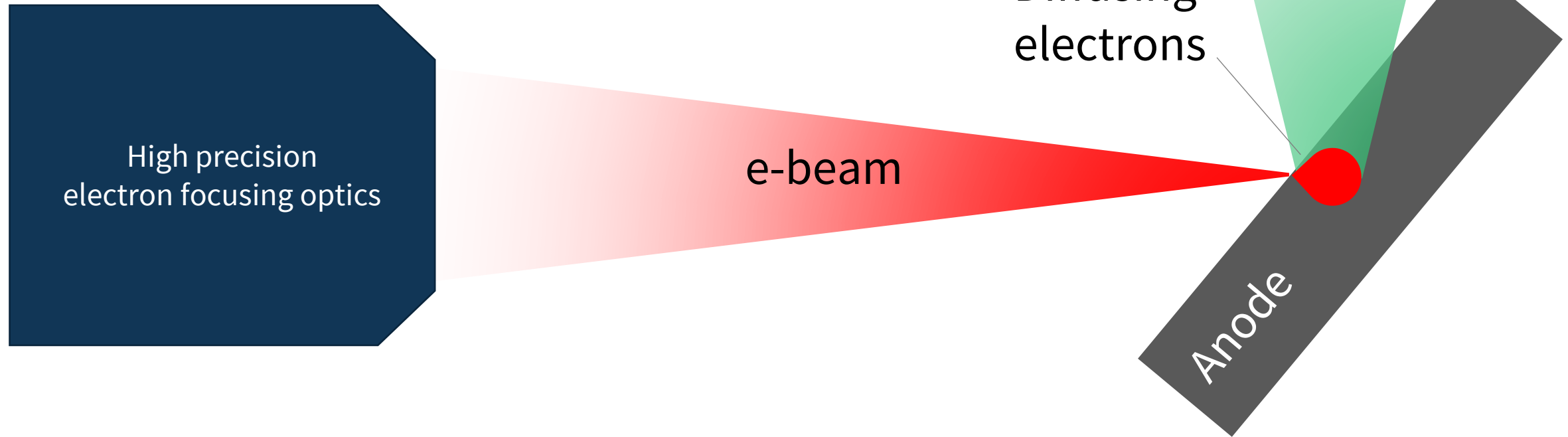
Brightness



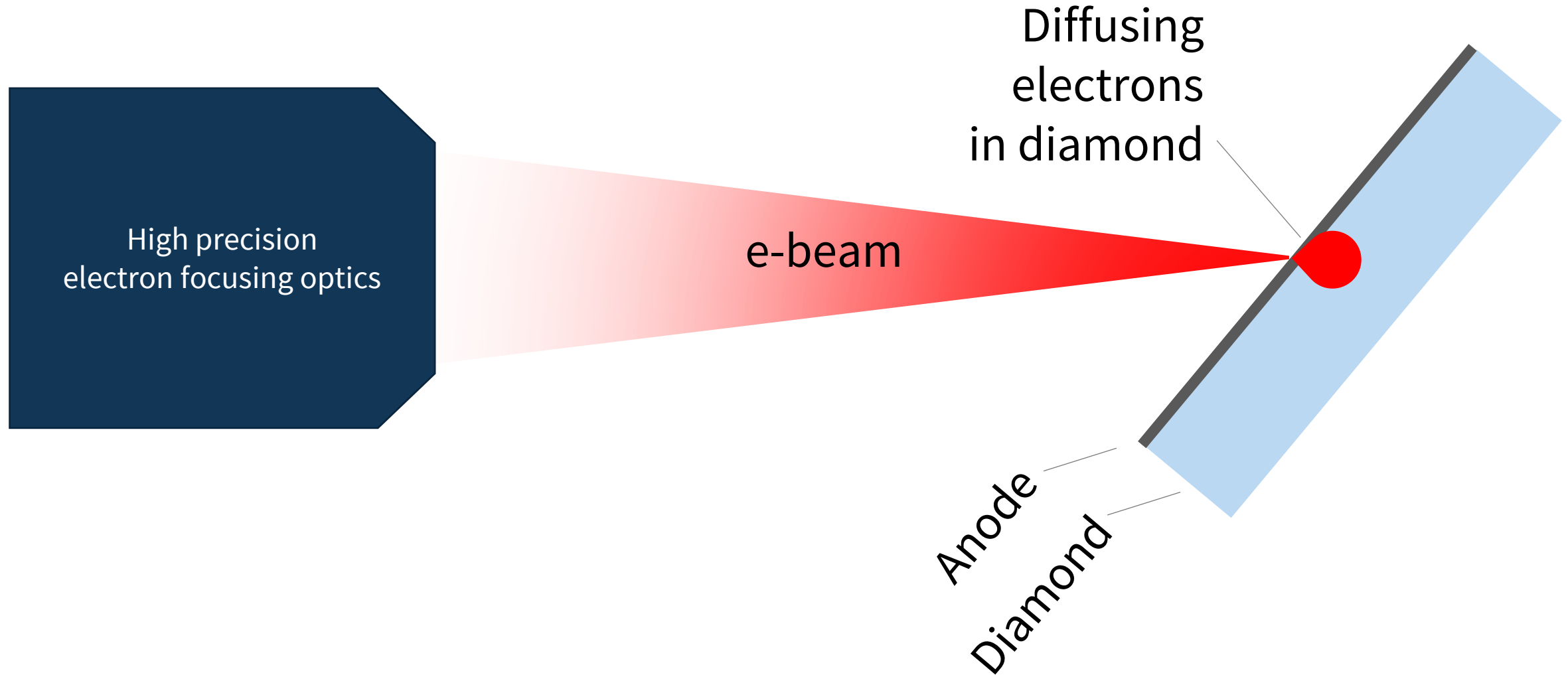
Higher resolution



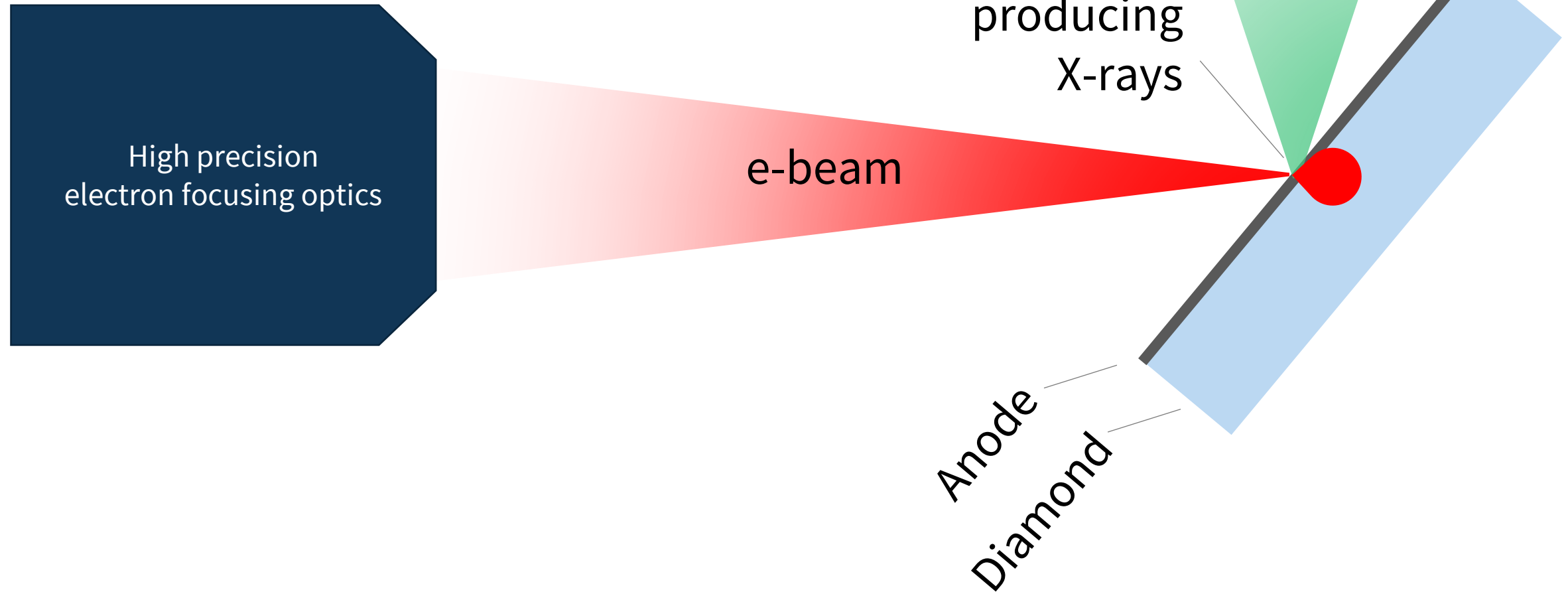
How to achieve small X-ray spots



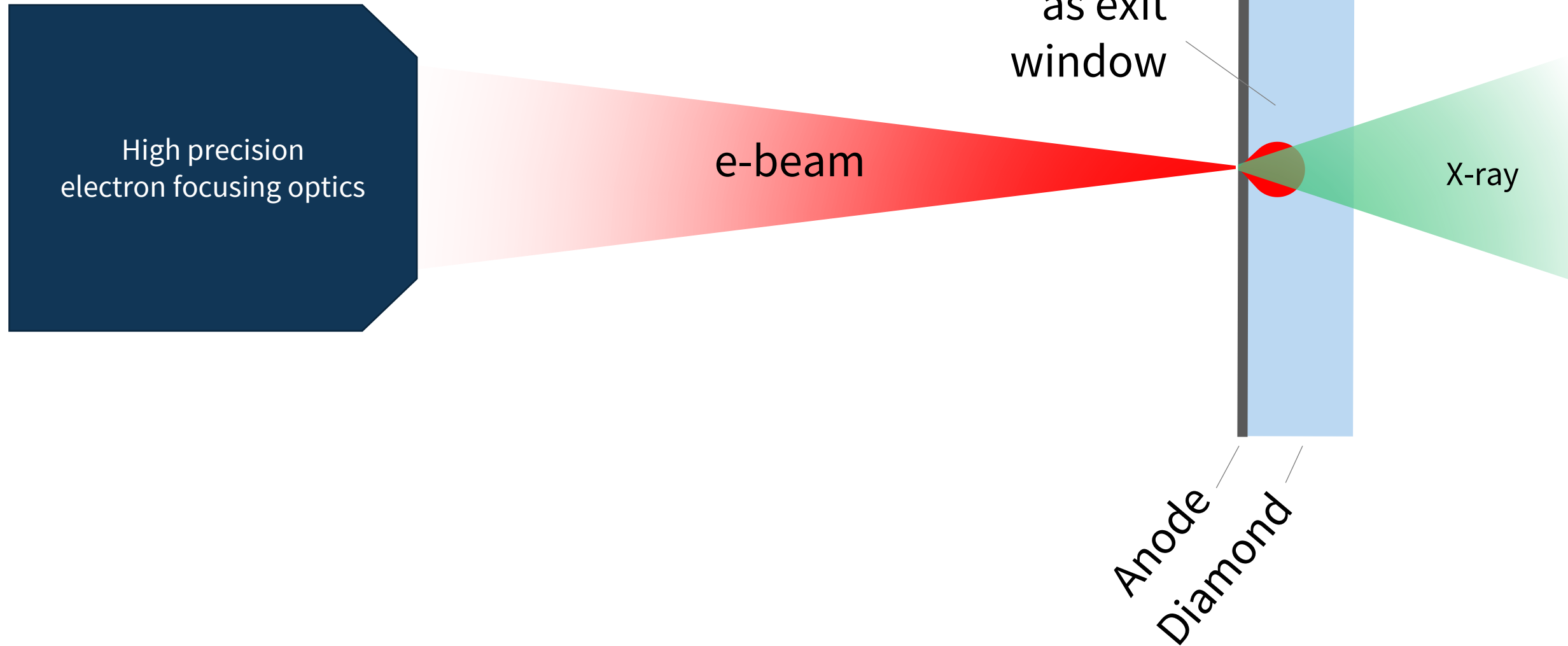
How to achieve small X-ray spots



How to achieve small X-ray spots



How to achieve small X-ray spots



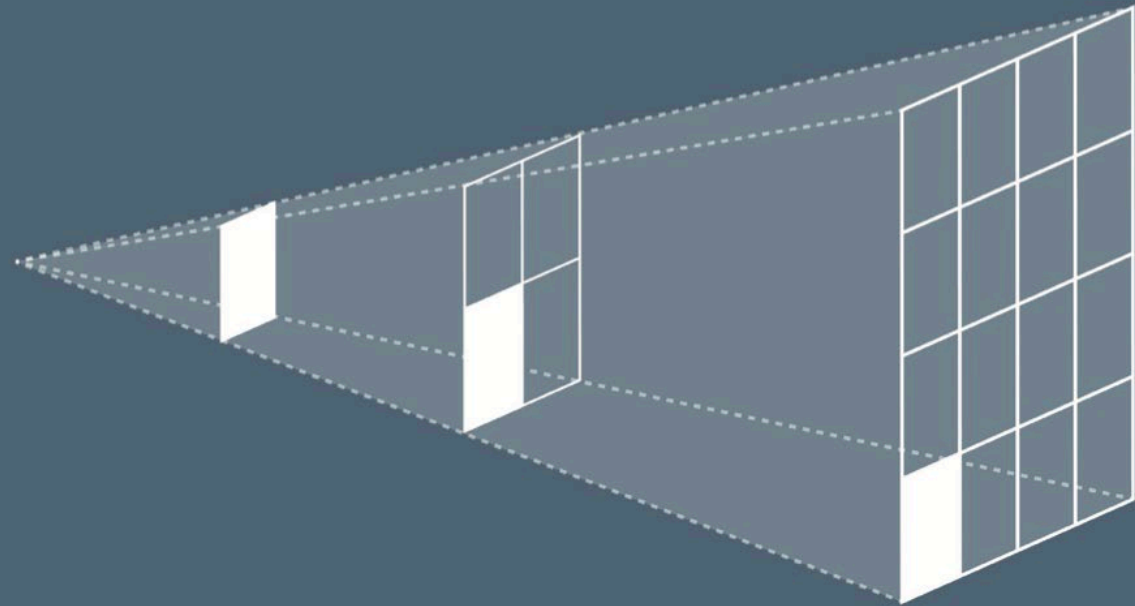
High resolution through geometric magnification

High resolution through
geometric magnification M :

- Minimise Source-Object distance (**SOD**)
- Select Magnification by adjusting Source-Detector distance (**SDD**)

$$M = \frac{SDD}{SOD}$$

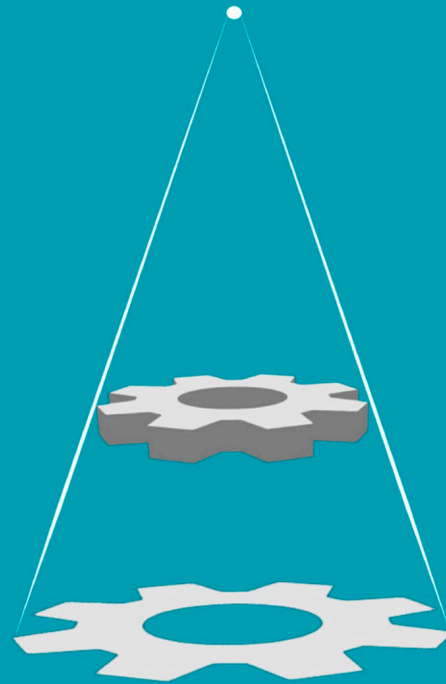
Inverse square law



Resolution limit: spot size and penumbral blurring

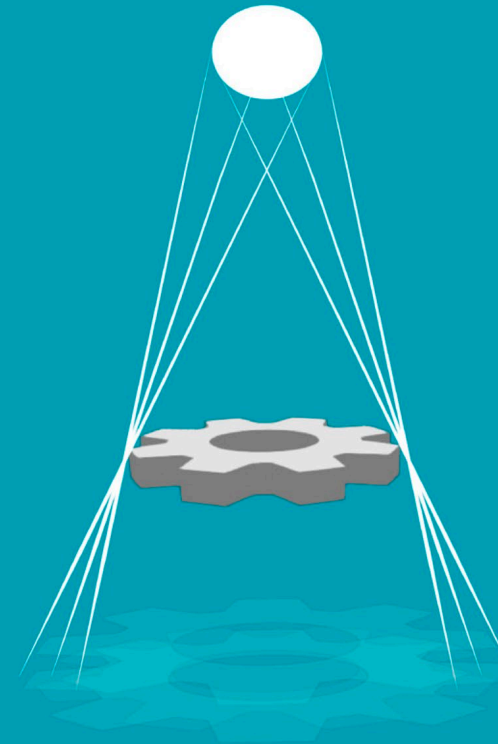
Resolution limit:

$\frac{1}{2}$ FWHM of x-ray spot
Assuming a Gaussian-like spot profile



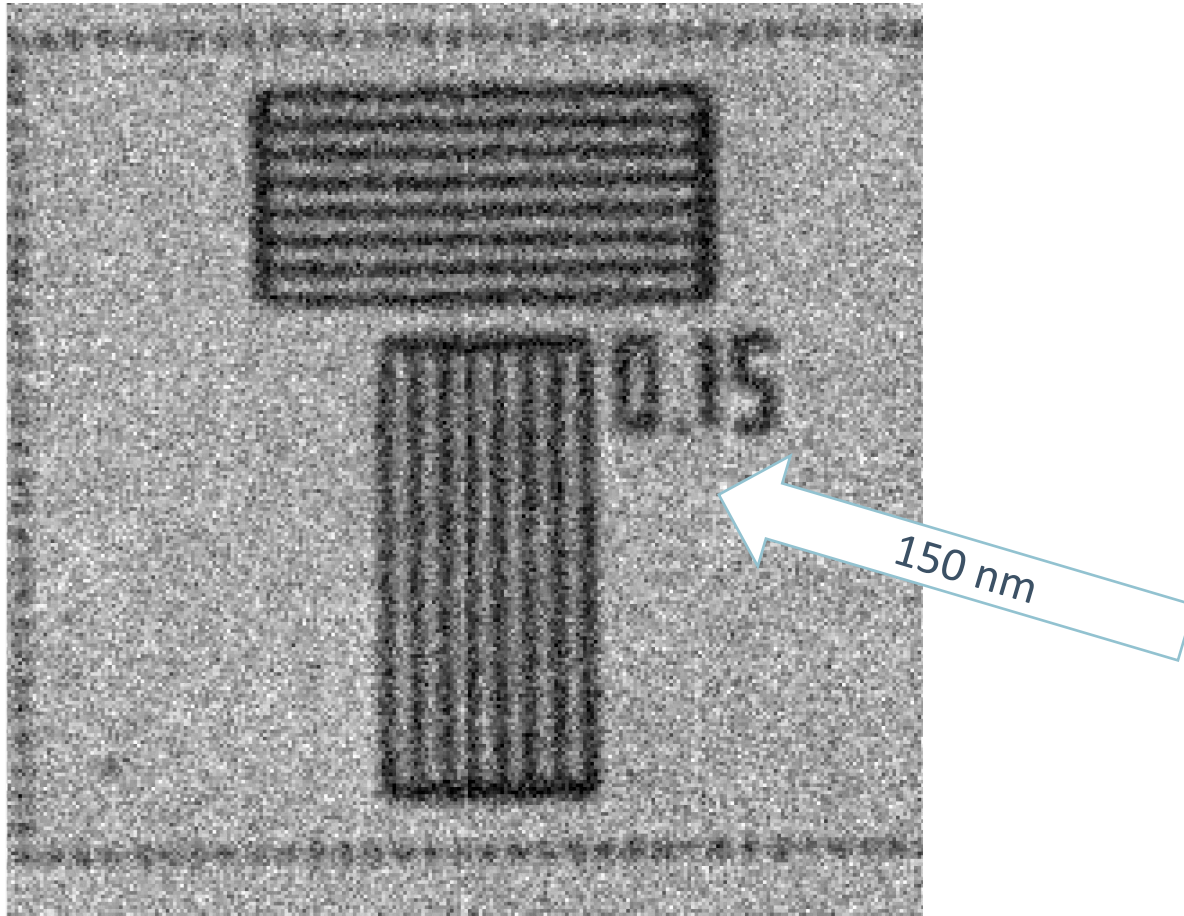
Penumbra blurring:

X-ray spot is projected onto the detector, limiting the achievable resolution

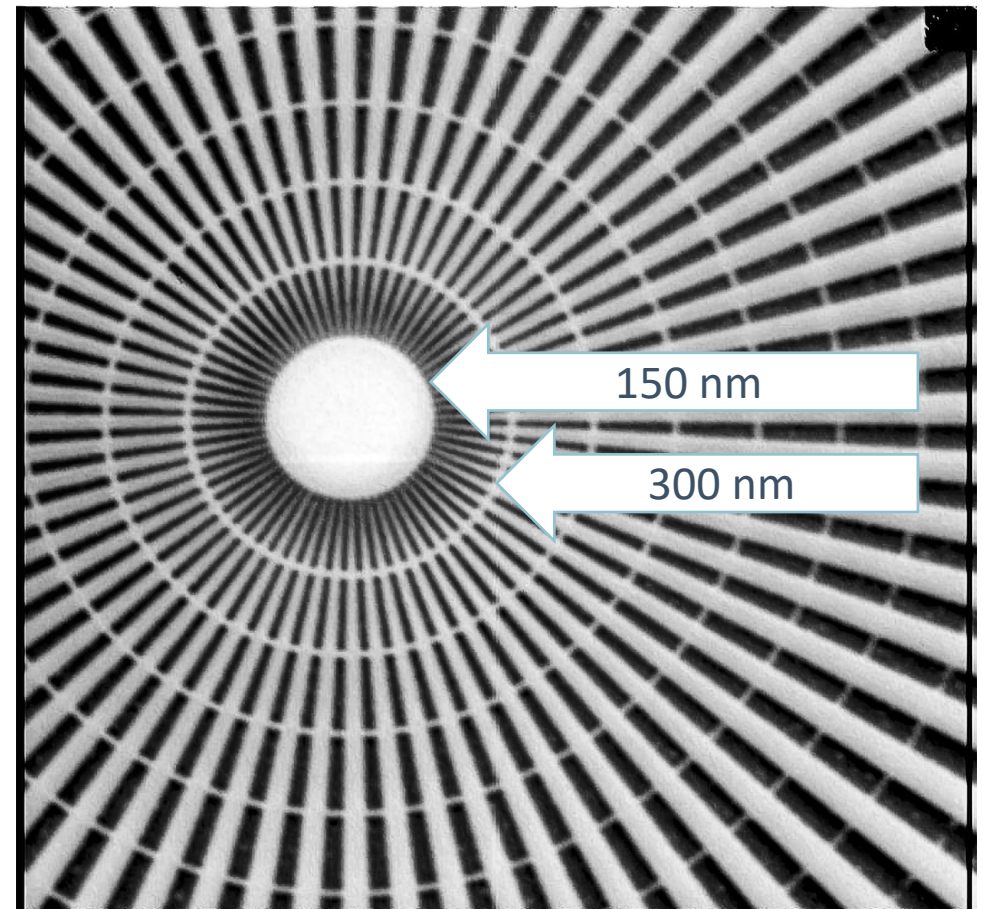


150 nm resolution without optics

JIMA RT RC-04

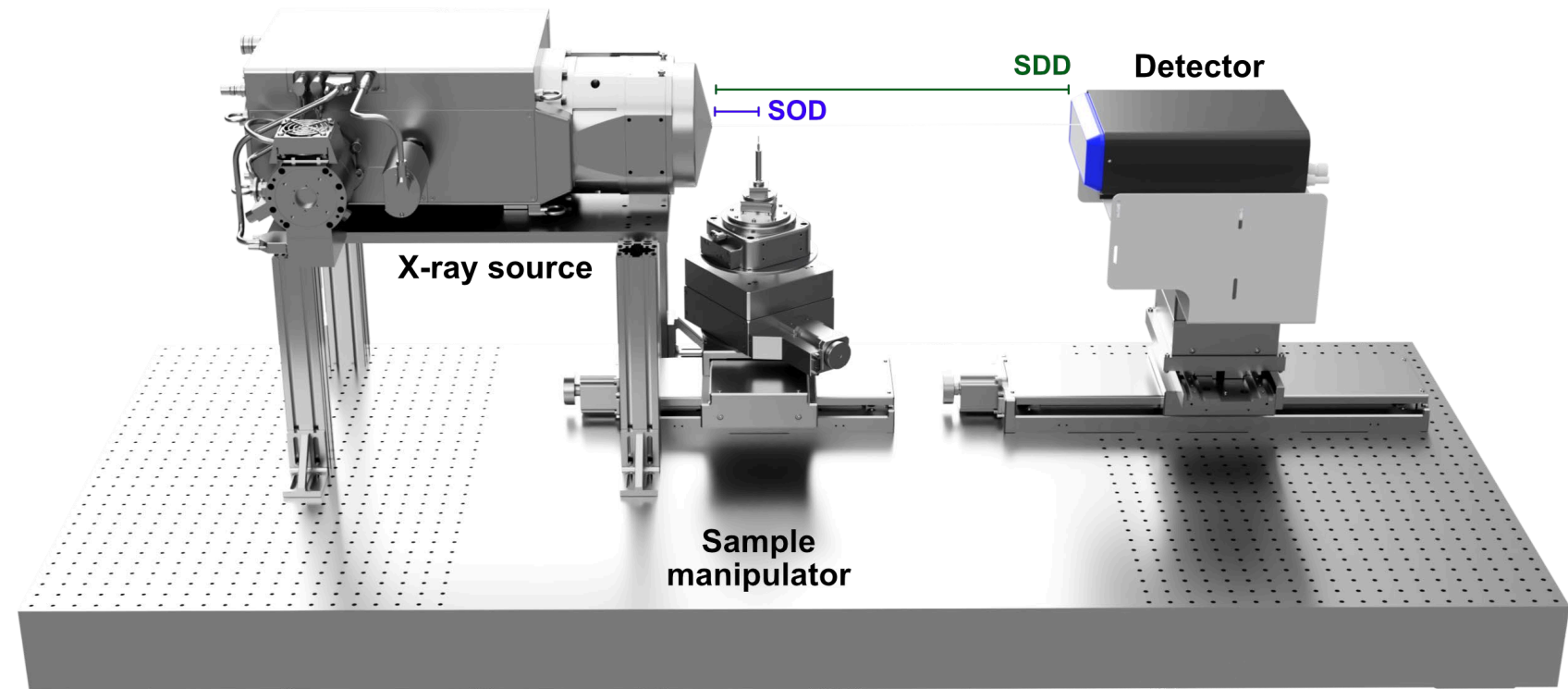


Siemens star



X-ray nano-CT

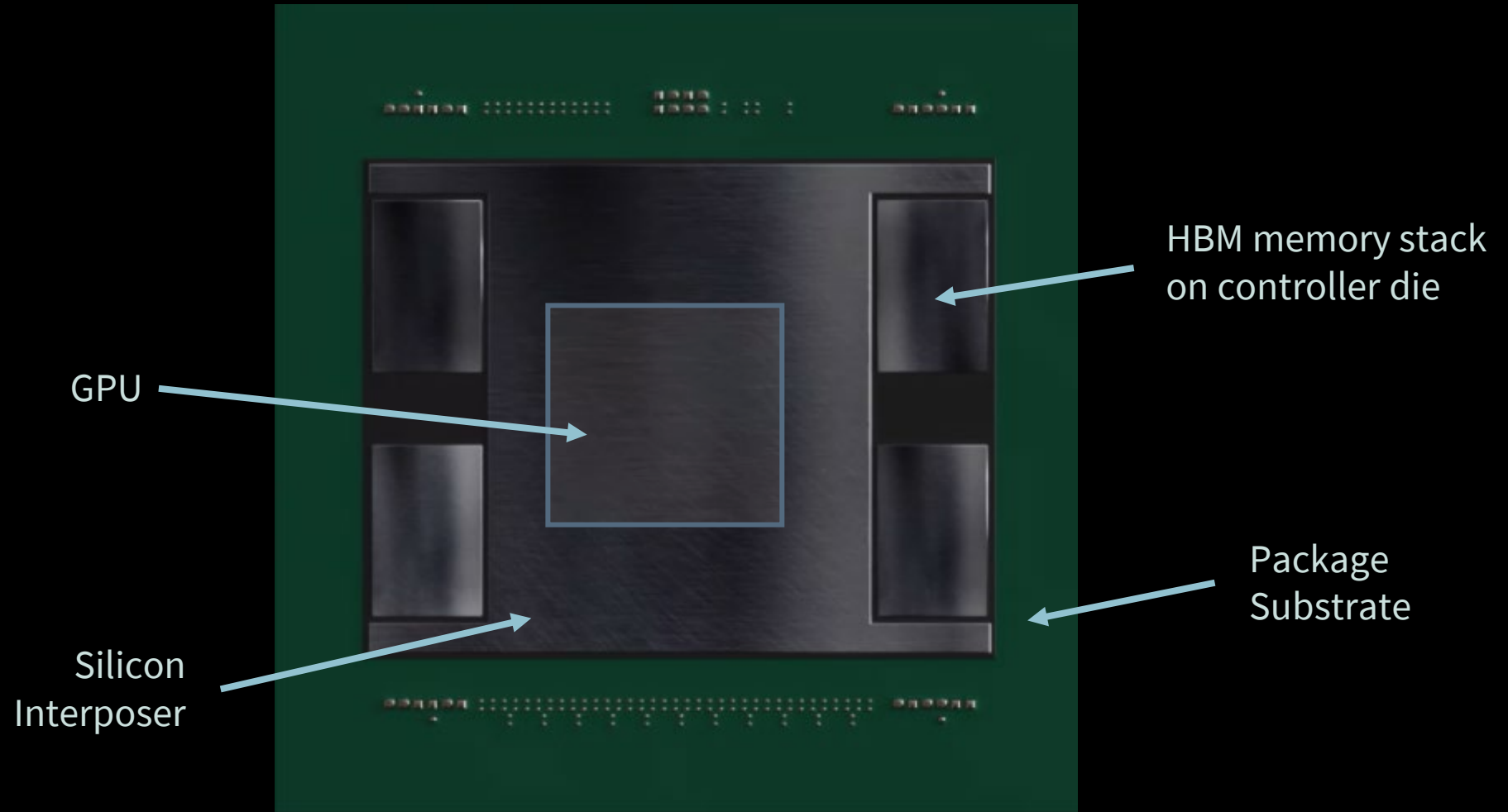
- Use high efficiency detectors with large pixels
 - Industrial FlatPanels with thick scintillators
 - Photon counting detectors
- Utilise inverse square law
 - Reduction of SOD by $\frac{1}{2}$ increases number of photons on sample by 4x



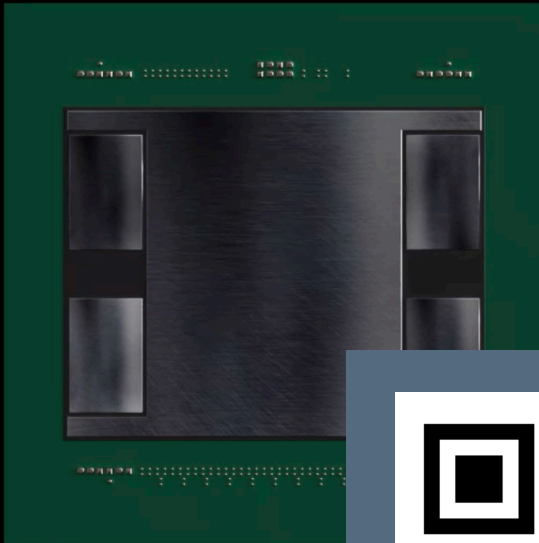
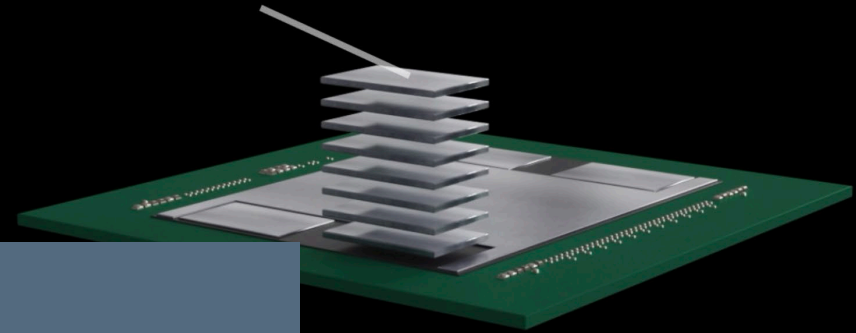


High-Bandwidth Memory (HBM)

Nano-CT in advanced packaging

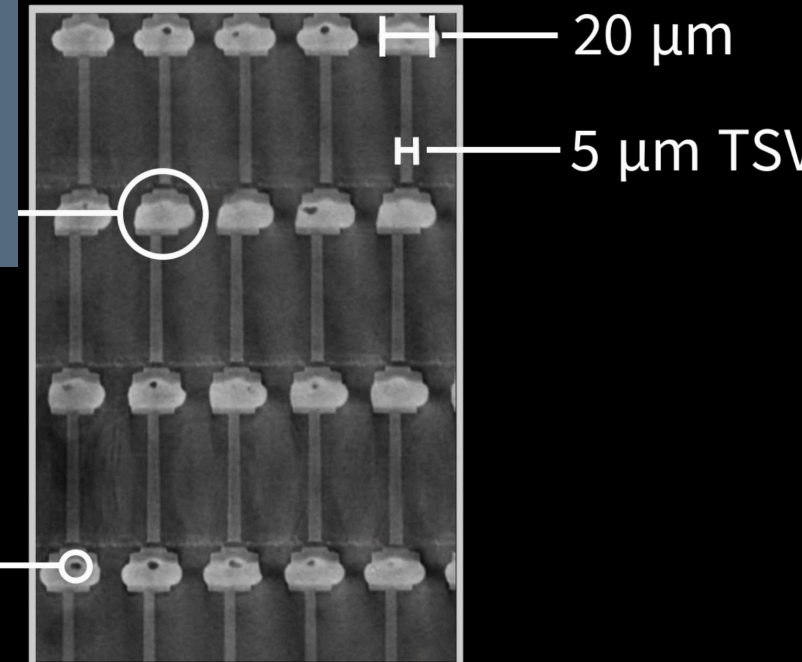
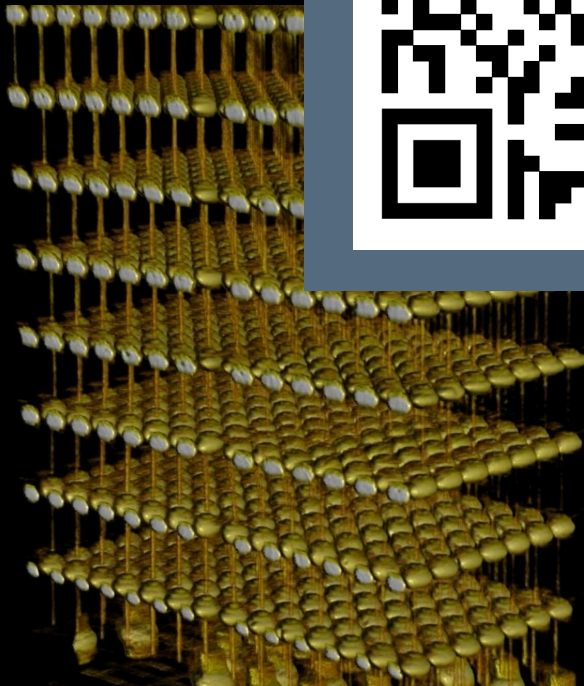


Commercially available
GPU with HBM



Video available
at:

<https://youtu.be/OT9j3JvEn80?si=0MSejJPhyMm2PqHw>



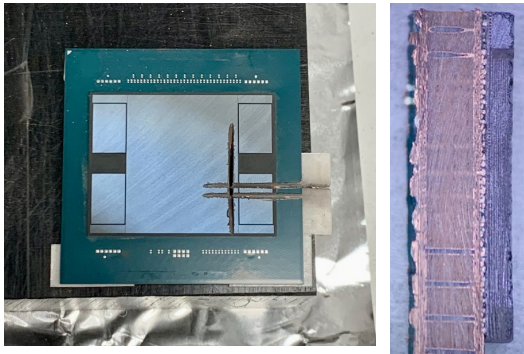
20 μm

5 μm TSV

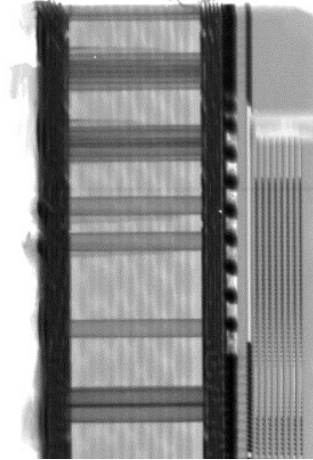
Void

Nano-CT in advanced packaging

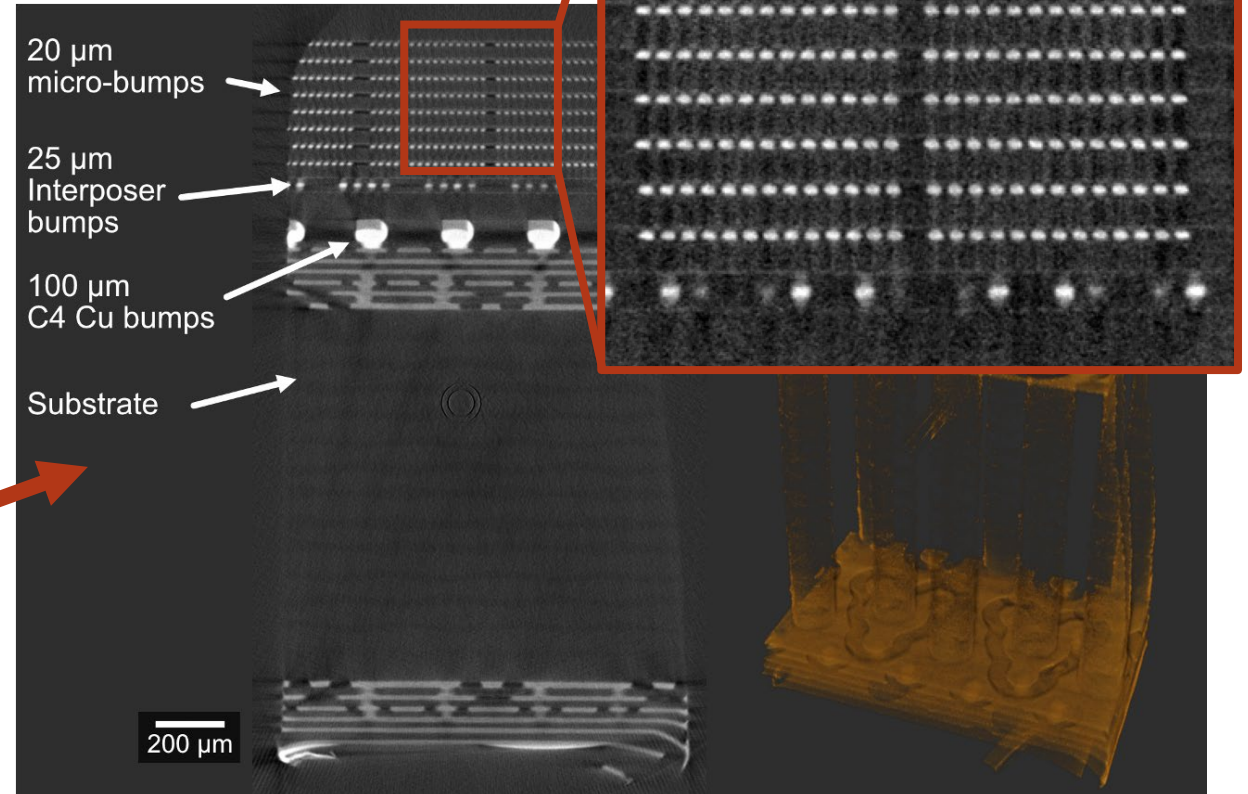
Commercially available GPU with HBM



2D X-ray overview



30 s overview scan



3D Memory(HBM) Silicon die
Base die Interposer PKG Substrate

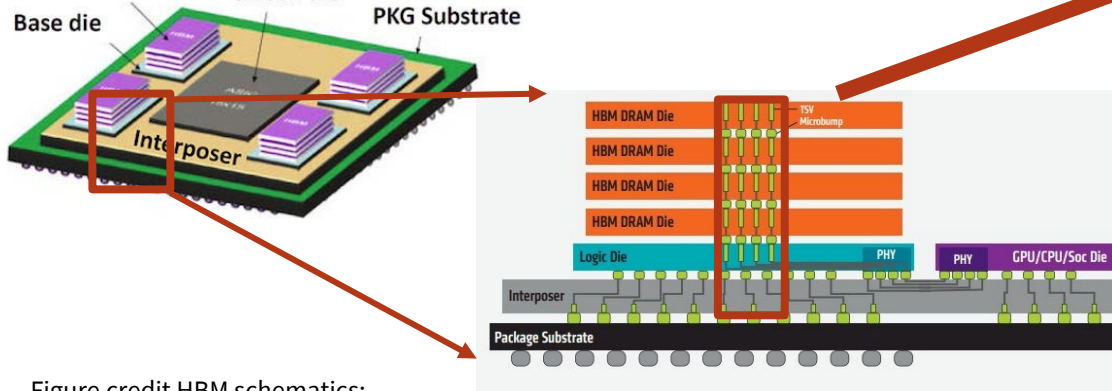


Figure credit HBM schematics:

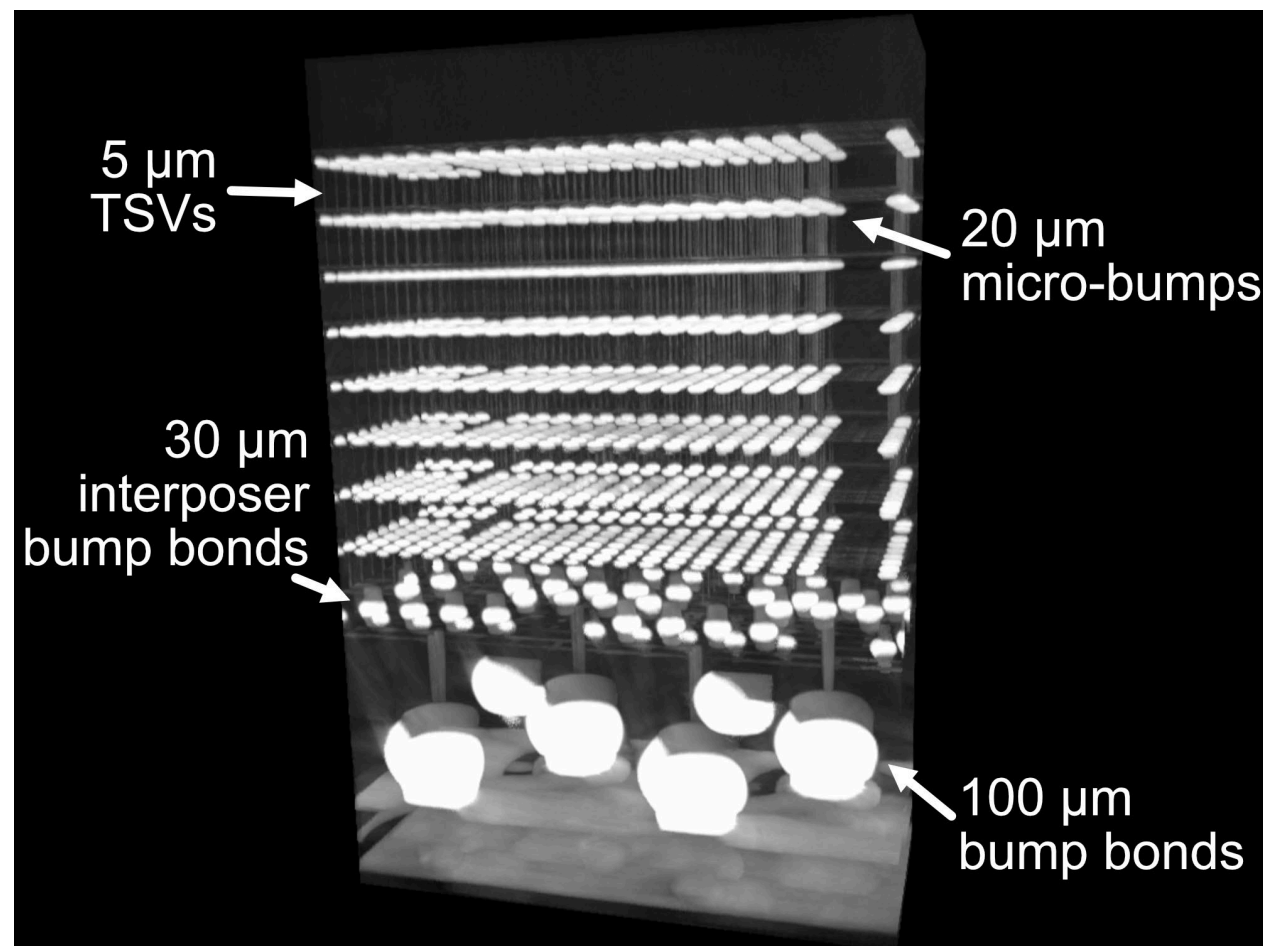
<https://www.eenewseurope.com/en/closing-the-memory-gap-can-advanced-fab-and-packaging-finally-realize-in-memory-processing/>

<https://www.amd.com/en/technologies/hbm>

X-ray image and 3D render: T. Dreier et al., ESREF 2024, Submitted to Microelectronics Reliability.

High-bandwidth memory

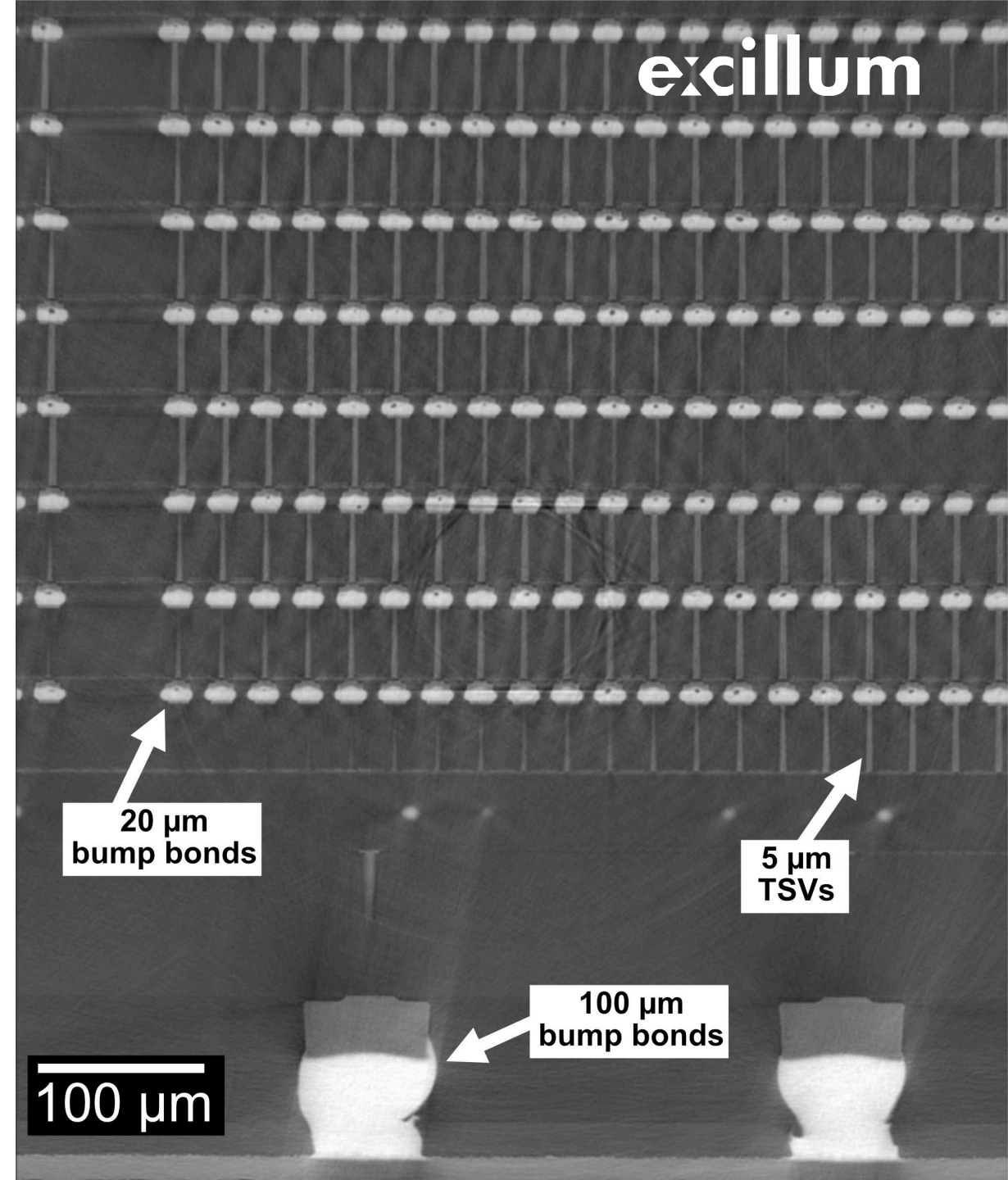
- Geometry
 - SOD = 3.65 mm
 - SDD = 390 mm
 - $p_{\text{eff}} = 700$ nm
- Scan settings
 - Projections: 2600
 - Rotation: 216 degrees
 - Exposure time: 10 s
 - Scan time: 7.2 h
- Source settings
 - Voltage: 100 kV
 - Spot size: 600 nm



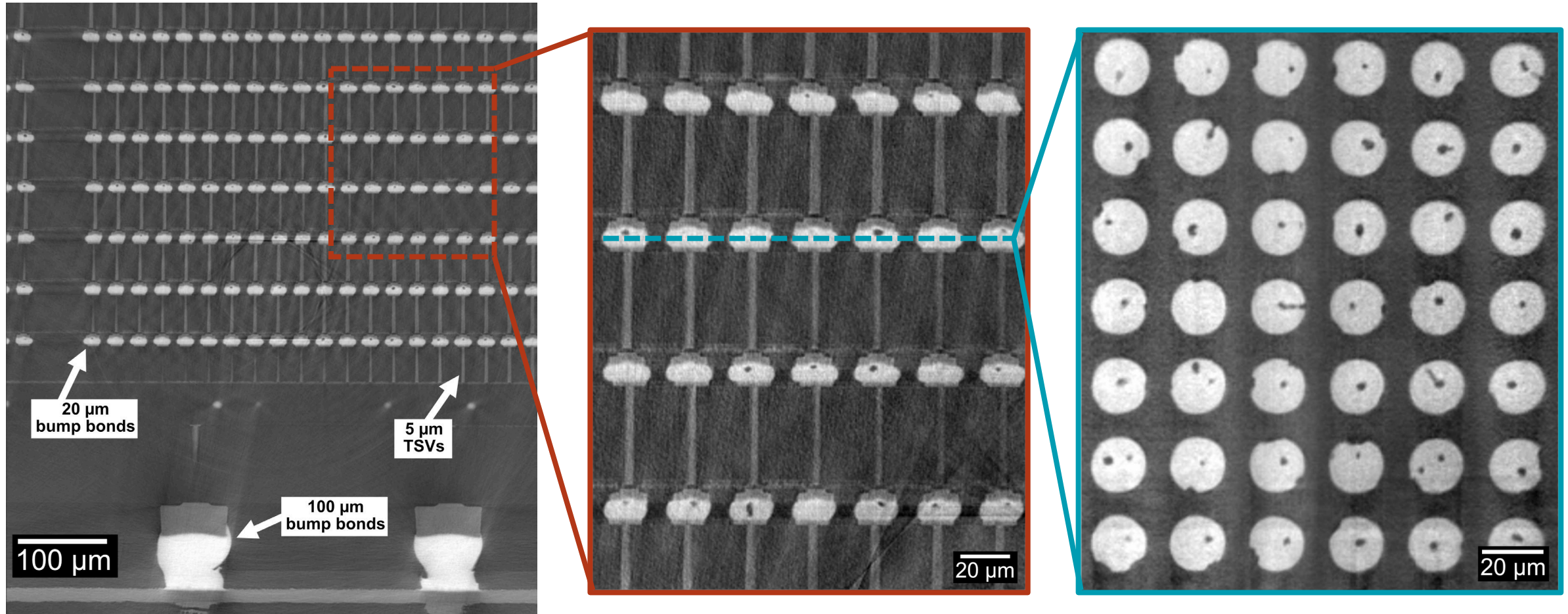
High-bandwidth memory

- 8 layer DRAM stack at sub-micron resolution
- Imaging of 5 μm TSVs
- Uniform resolution in all directions
- Capture >1000 individual bump bonds and voids¹

¹ T. Dreier et al., ESREF 2024, submitted to Microelectronics Reliability.

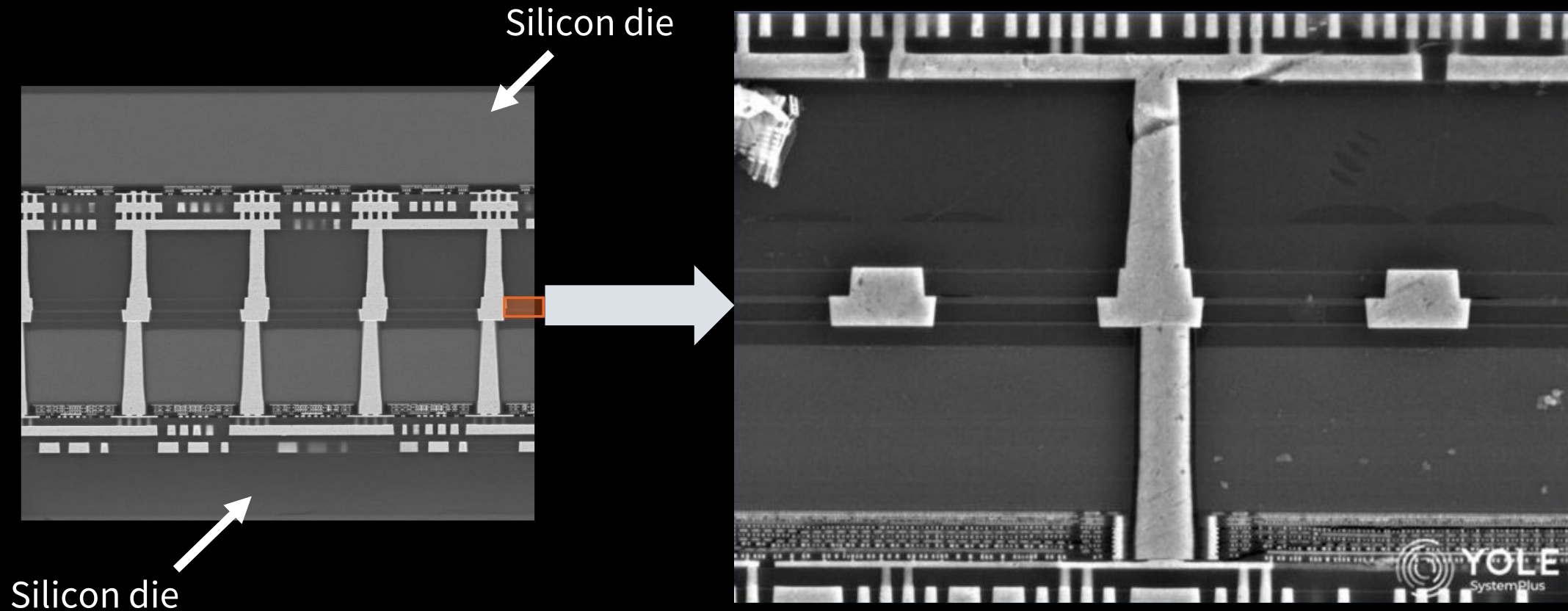


High-bandwidth memory



Hybrid Bonding

Hybrid bonding

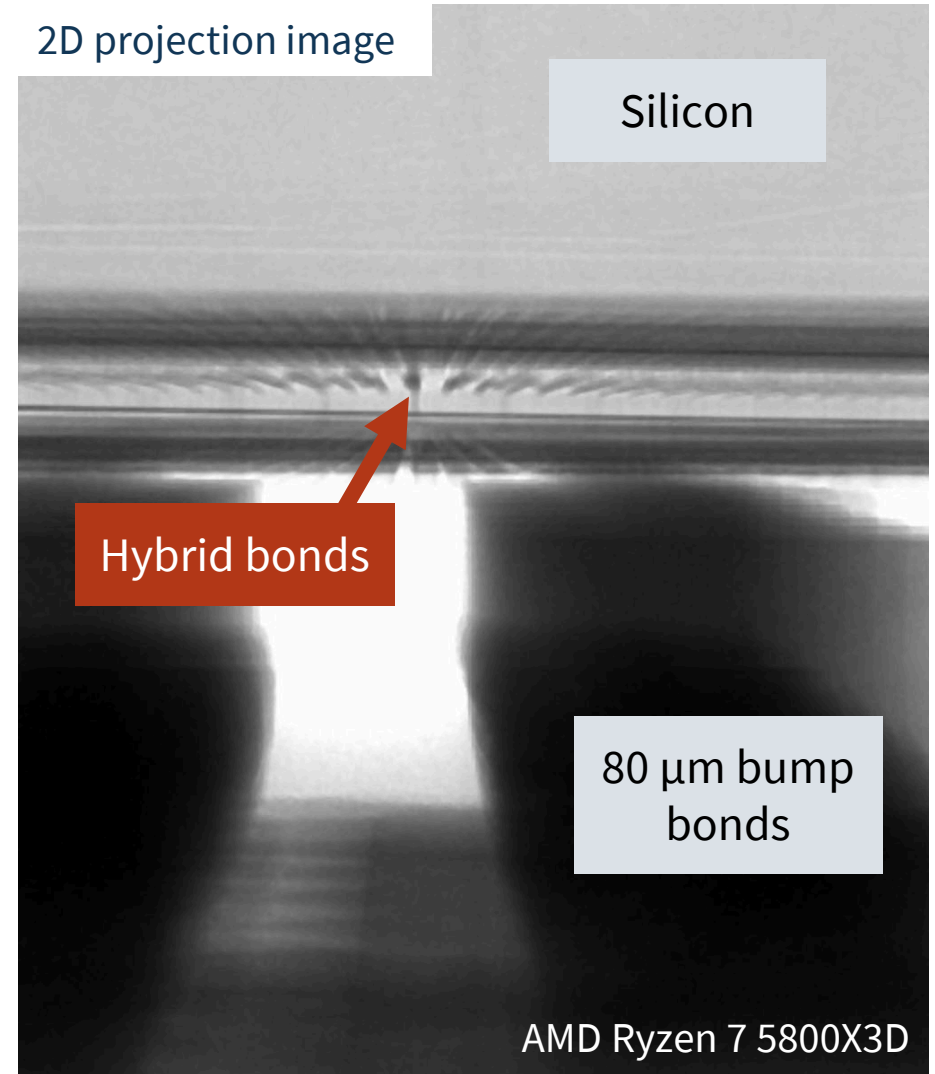
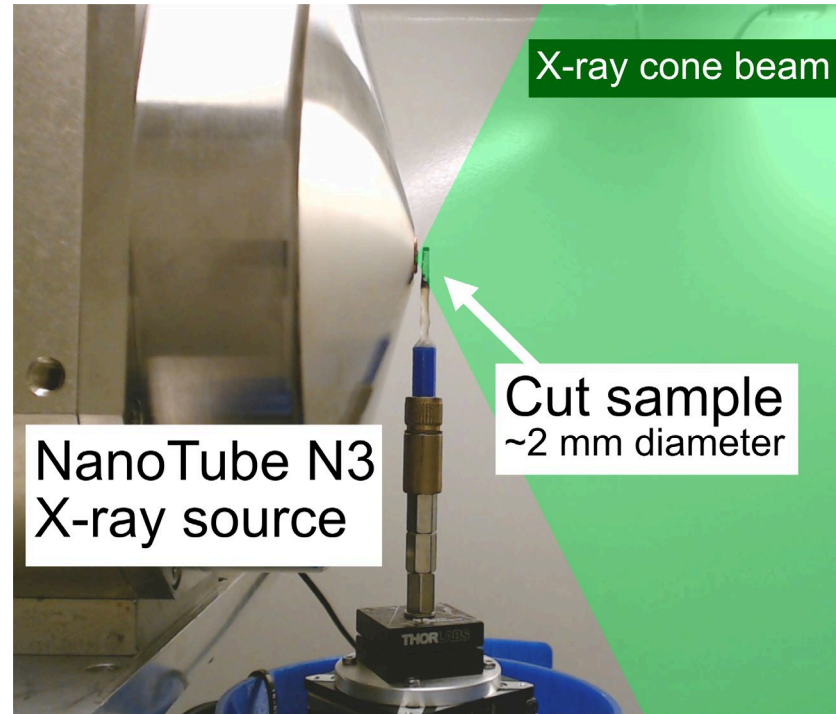


Direct Cu-Cu bonding of 2 Silicon dies

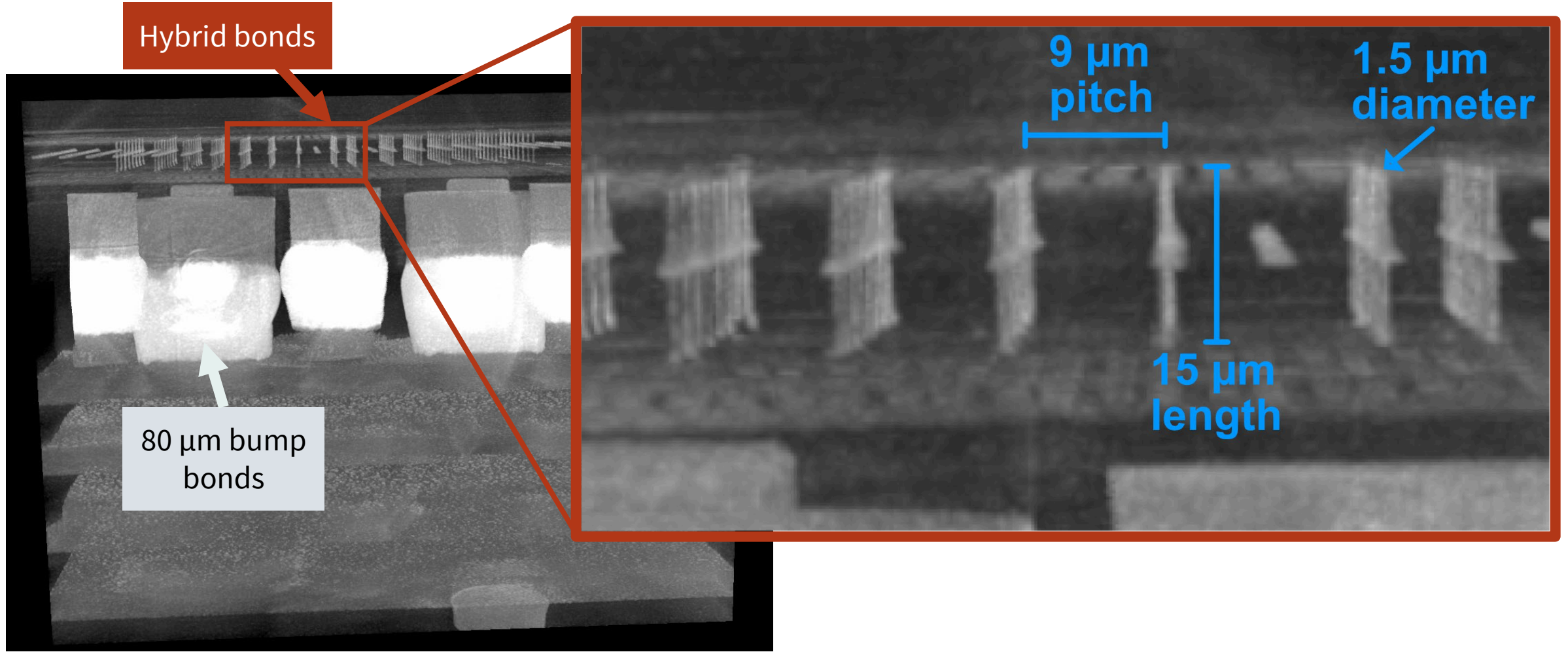
Image credit: <https://www.servethehome.com/amd-milan-x-delivers-amd-epyc-caches-to-the-gb-era/amd-epyc-7003x-milan-x-hybrid-bonding/>
and: <https://www.yolegroup.com/strategy-insights/innovation-beyond-moores-law-advanced-packaging-explores-new-frontiers/>

Hybrid bonding

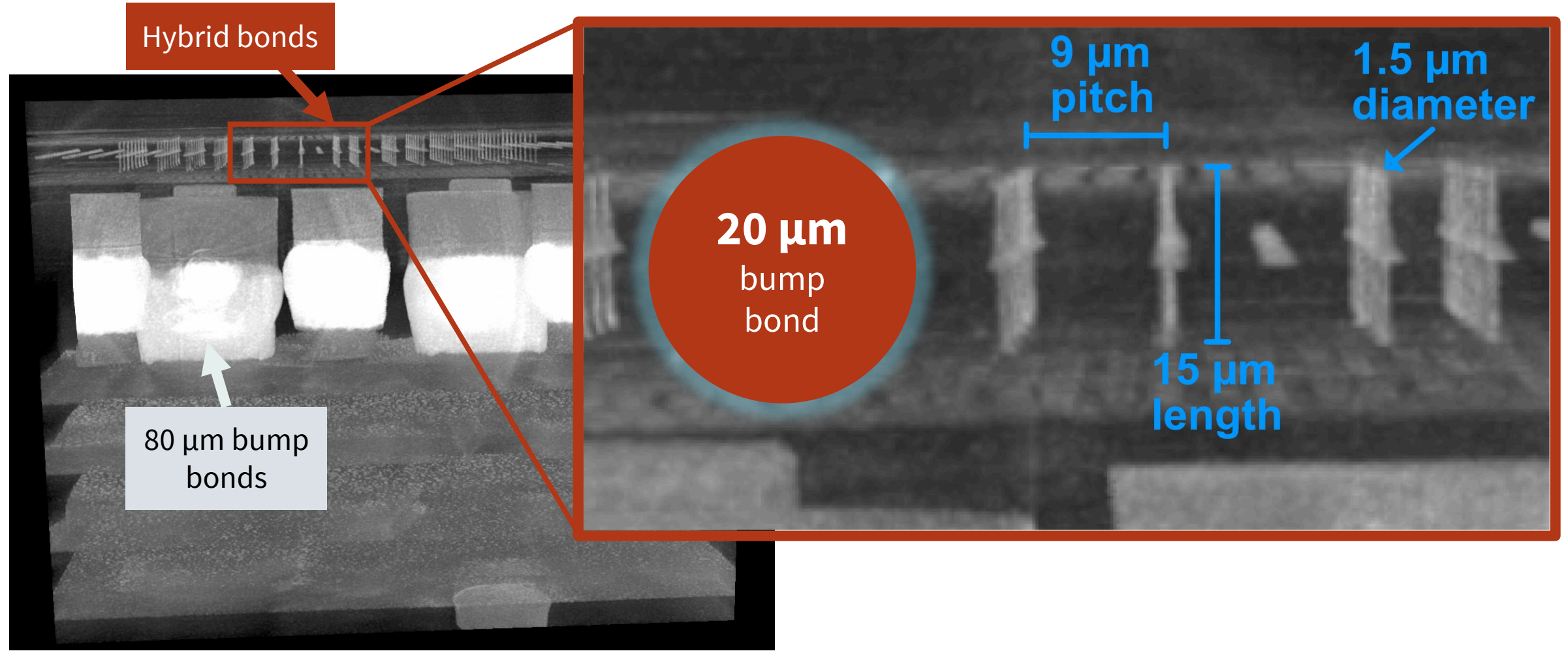
- Geometry
 - SOD = 2.29 mm
 - SDD = 490 mm
 - $p_{\text{eff}} = 350 \text{ nm}$
- Scan settings
 - Projections: 2160
 - Rotation: 216 degrees
 - Exposure time: 10 s
 - Scan time: 6 h
- Source settings
 - Voltage: 80 kV
 - Spot size: 500 nm

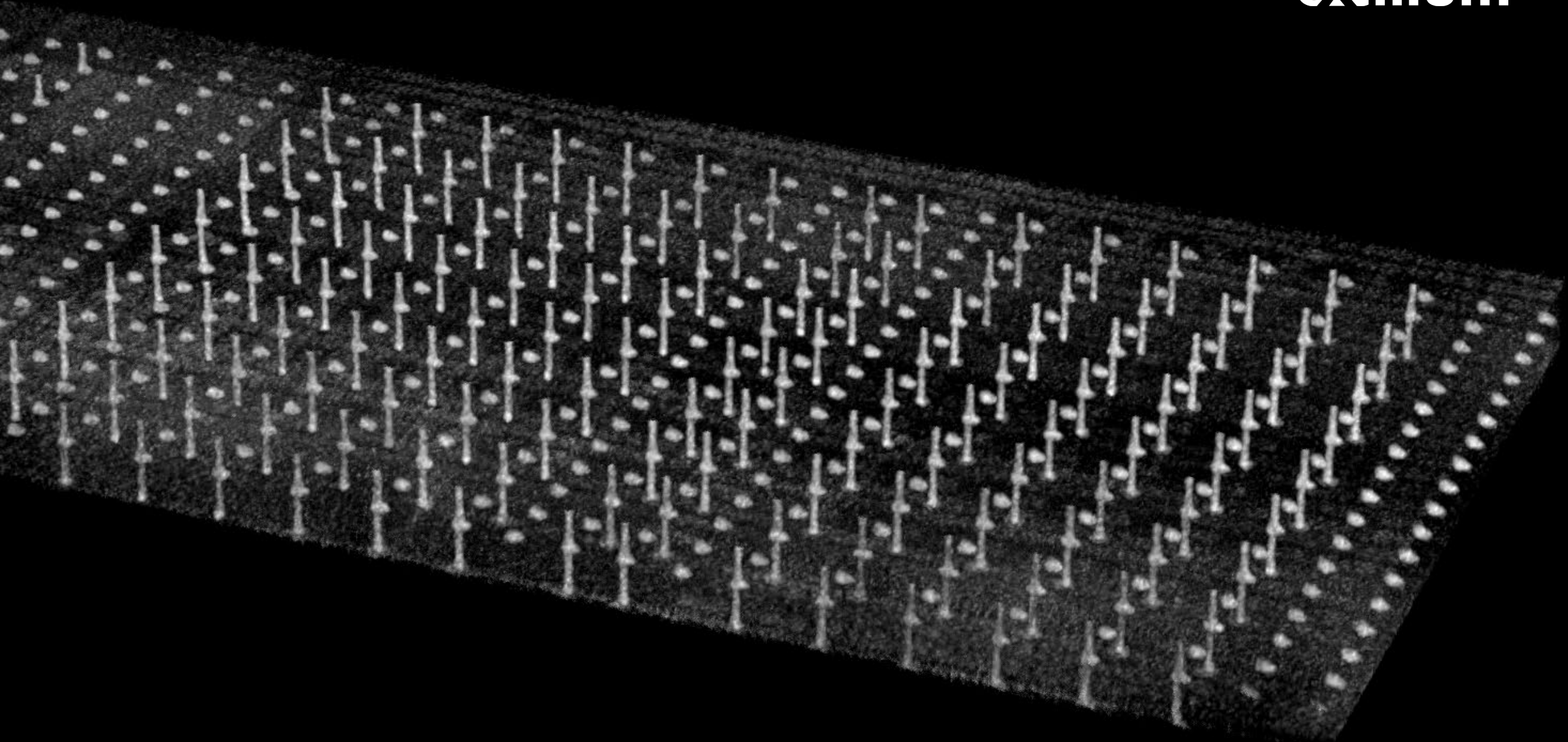


Hybrid bonding

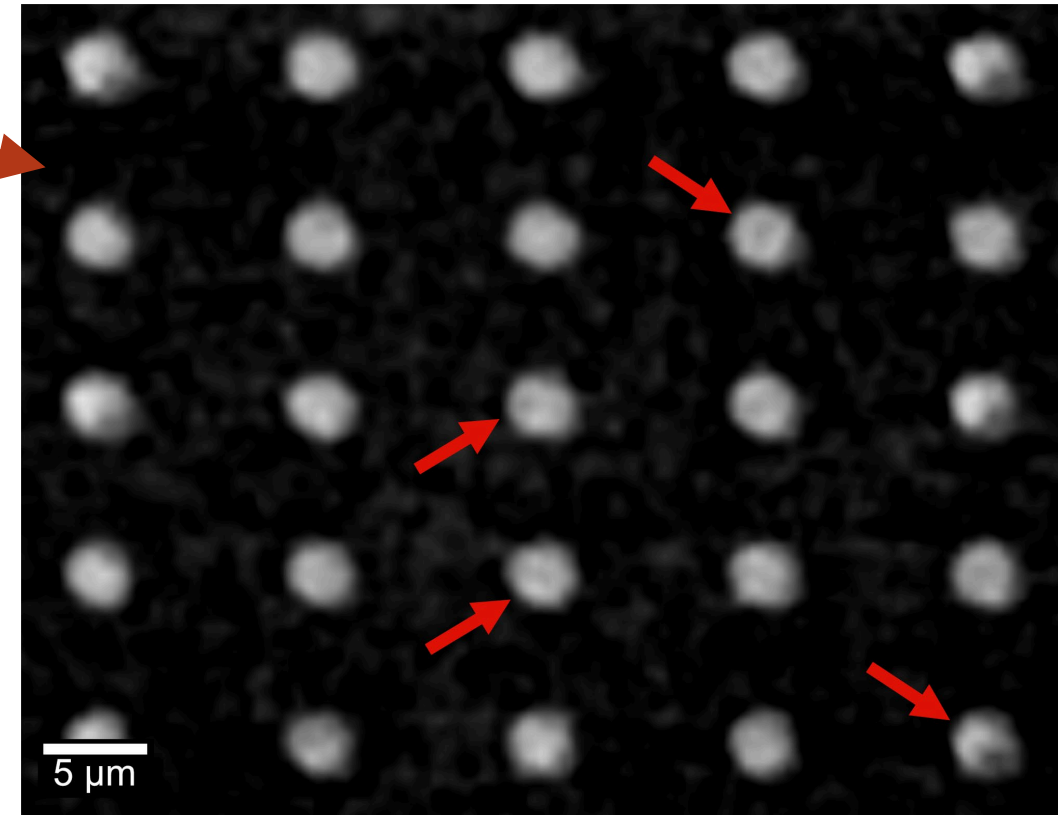
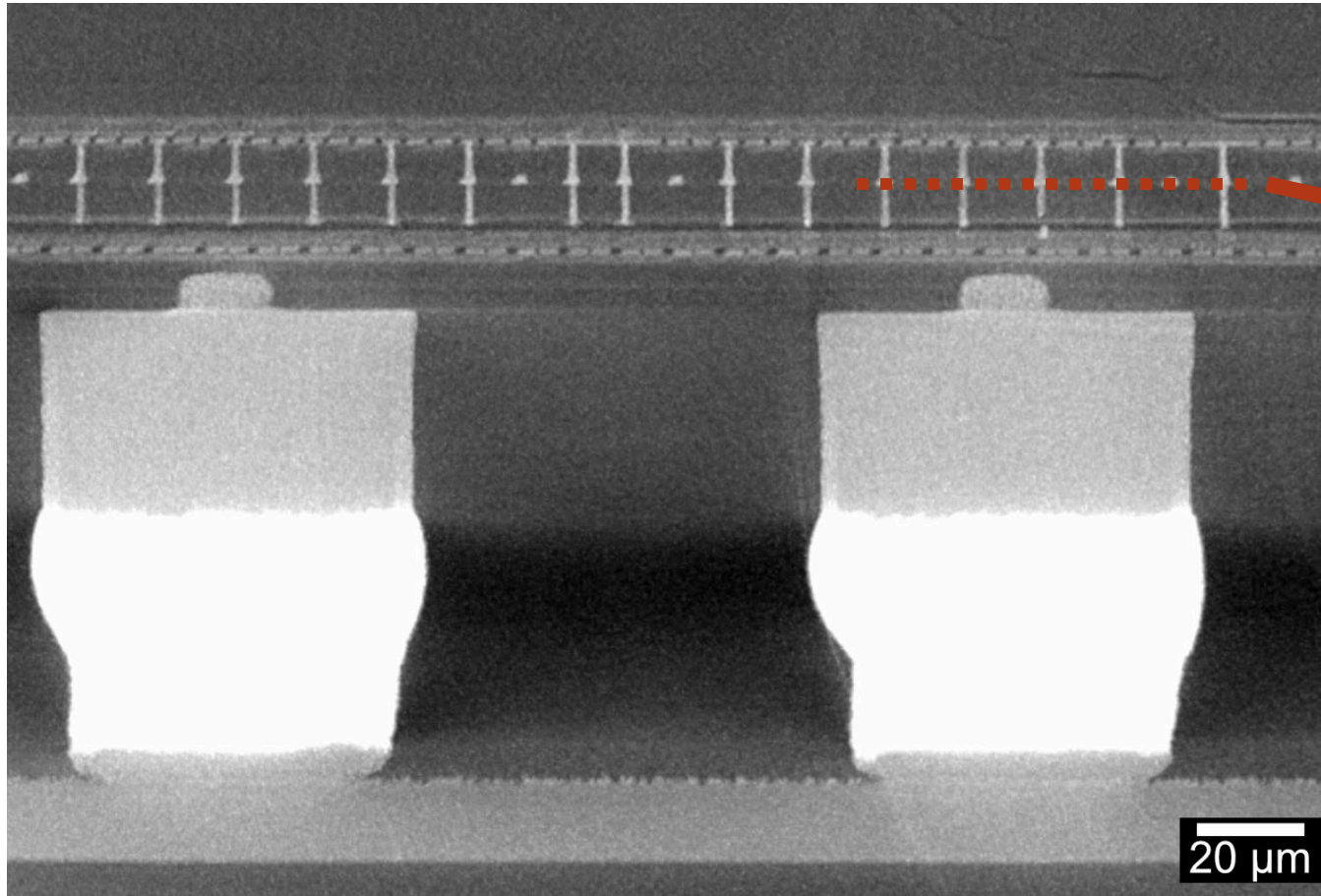


Hybrid bonding





Hybrid bonding



Conclusions



High resolution X-ray CT without optics



Imaging of micro-bumps and hybrid bonding



Package level failure analysis enabled by X-ray CT

Intel EMIB scanned using a Waygate Nanomex

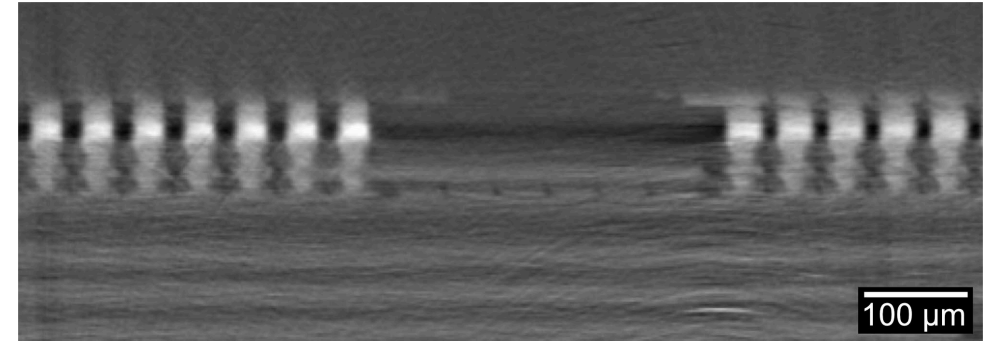


Image copyright : T. Dreier et al., ISTFA 2024, San Diego, USA
International

© ASM



Intel EMIB scanned using a NanoTube-based system

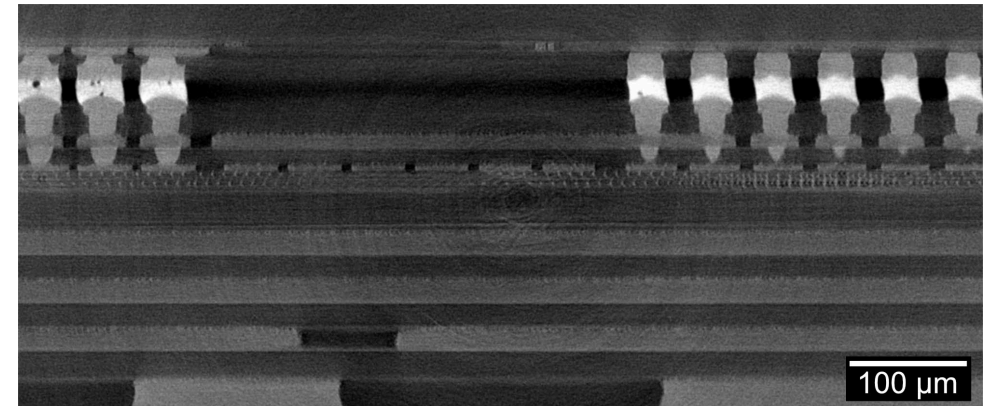


Image copyright : T. Dreier et al., ISTFA 2024, San Diego, USA
International

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Acknowledgements

DECTRIS
detecting the future

DECTRIS Ltd. is acknowledged for providing the used detector and their support.



HiCONNECTS project has received funding from Chips Joint Undertaking (Chips JU) under grant agreement No 101097296. Chips JU receives support from the European Union's Horizon Europe research and innovation programme and Austria, Italy, Germany, Netherlands, Israel, Finland, Switzerland, Hungary, Sweden, Turkey, France, Denmark and Romania.

The source for X-ray innovation

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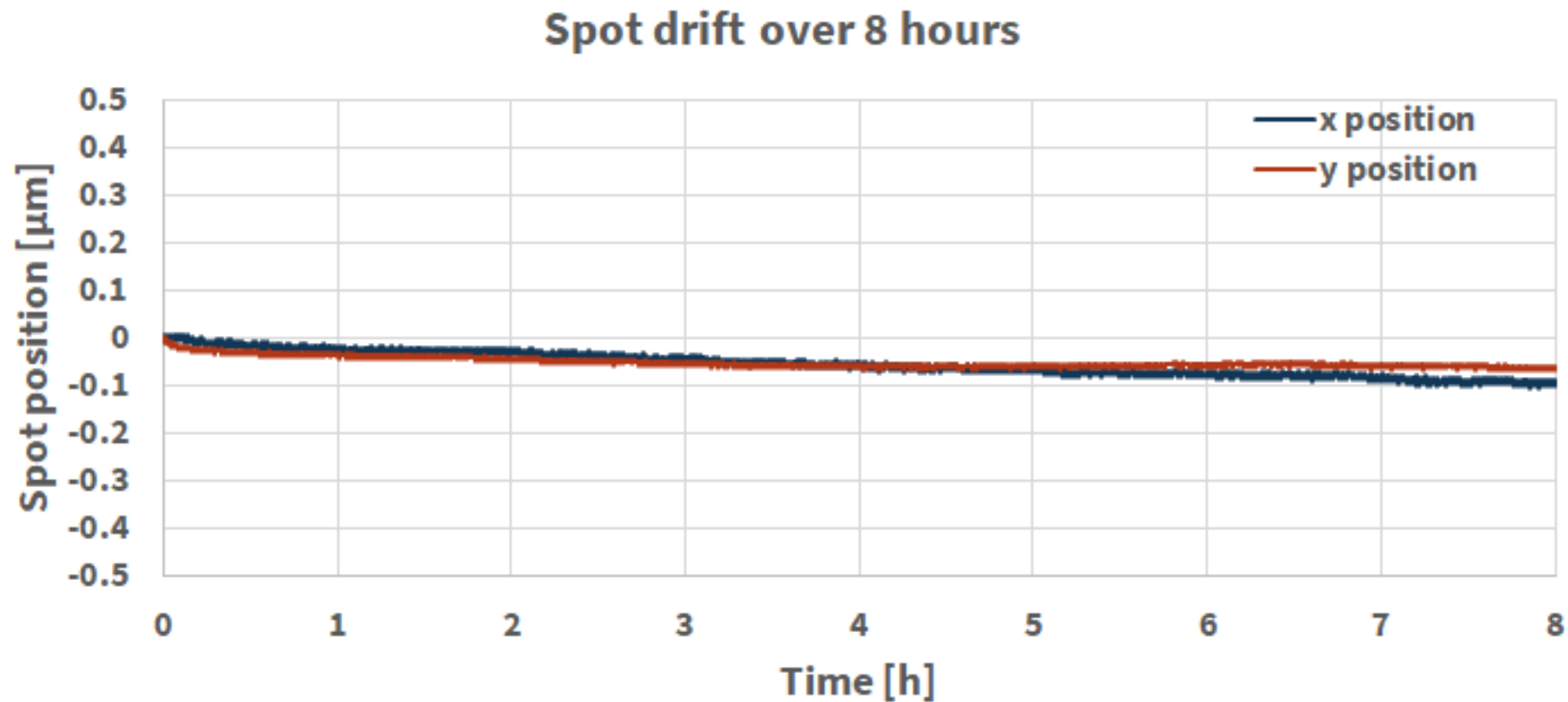
Application Scientist
till.dreier@excillum.com

Appendix



excillum

NanoTube N3 の優れた安定性

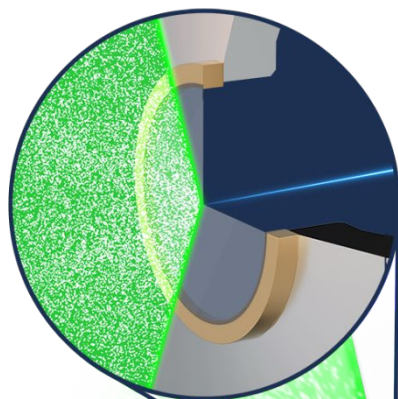


メンテナンスが最小限の開放型X線管！

Long lifetime and minimal maintenance

ダイヤモンド上の
タングステン透過
ターゲットの寿命
は5年以上。

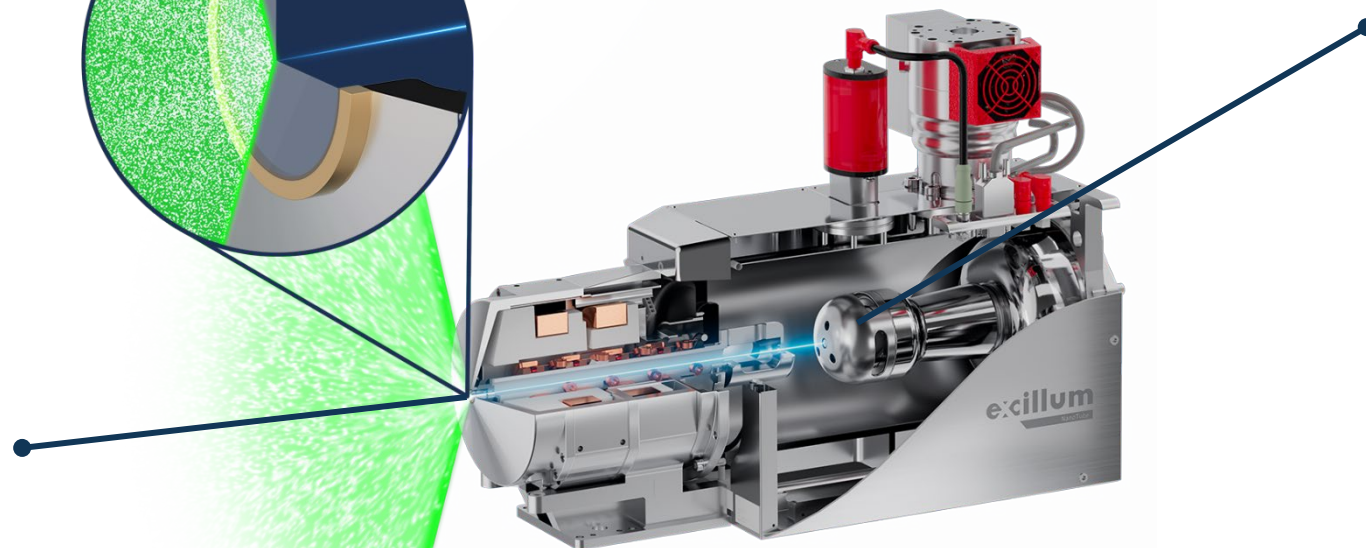
カソードの全寿命に
わたり、X線管の性
能は一定です。



平均寿命が 2500 時間以上のカソード

>5000 時間 (>0.5 μm 分解能および >100 kV で動作する場
合)

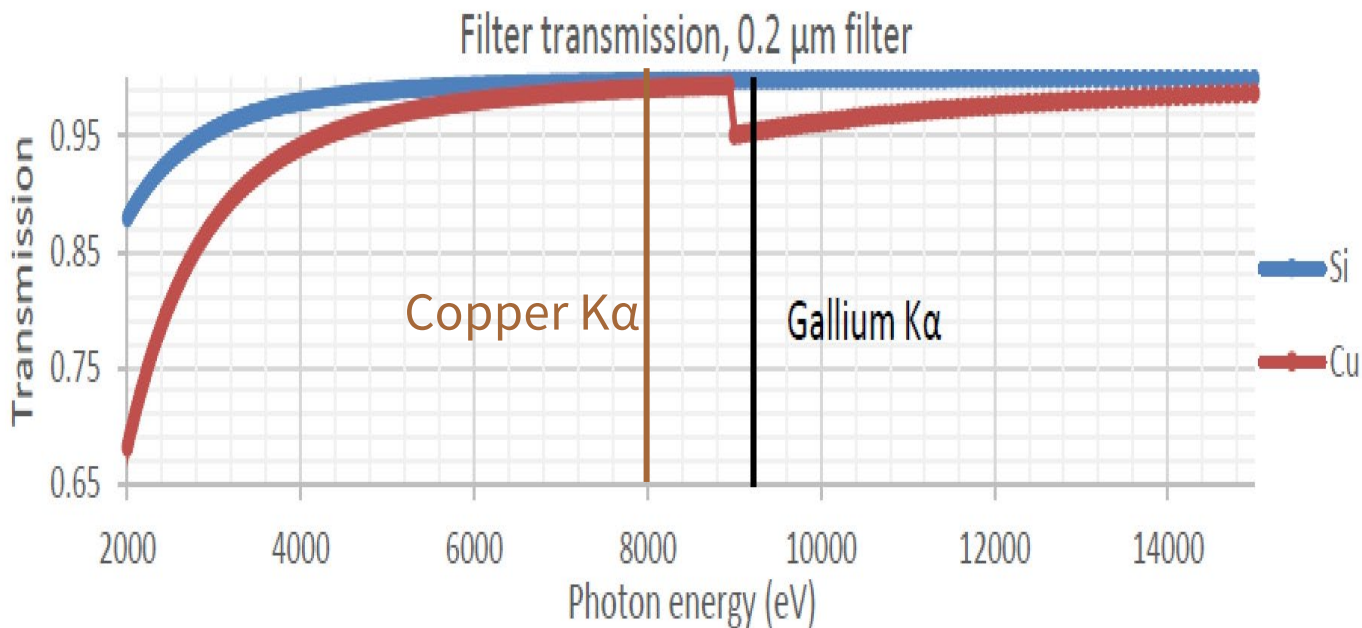
カソード交換時、現場でのダウンタイムは 4 時間未満



- 200時間ごとの自動キャリブレーションを推奨しています。
- カソード交換時まで、その他のメンテナンスは必要ありません。

MetalJetを用いたX線顕微鏡

Gaによる優れたSi/Cuコントラスト



Zeiss Xradia Ultraに搭載されたMetalJet D2+

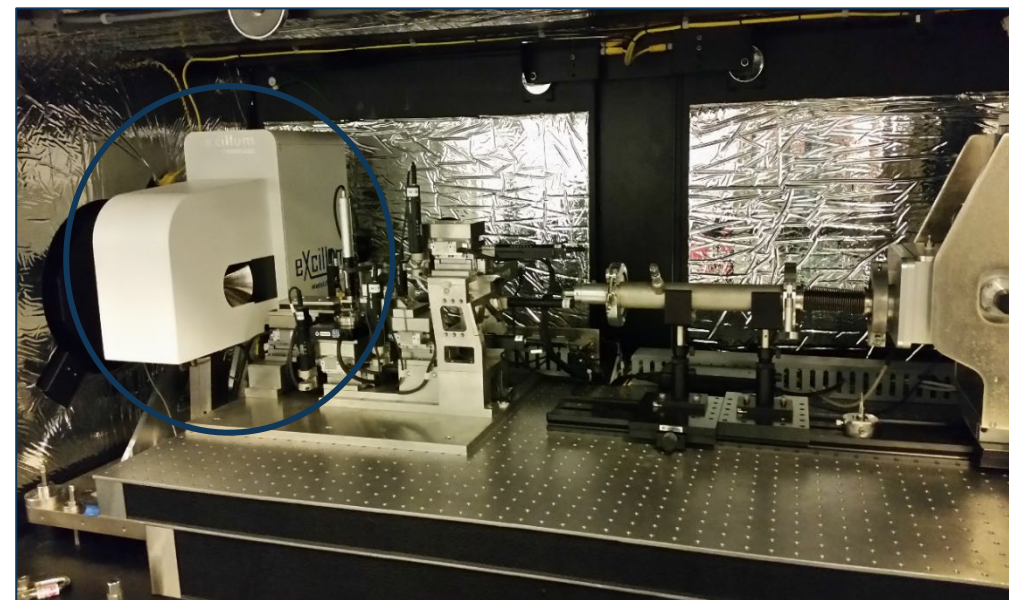
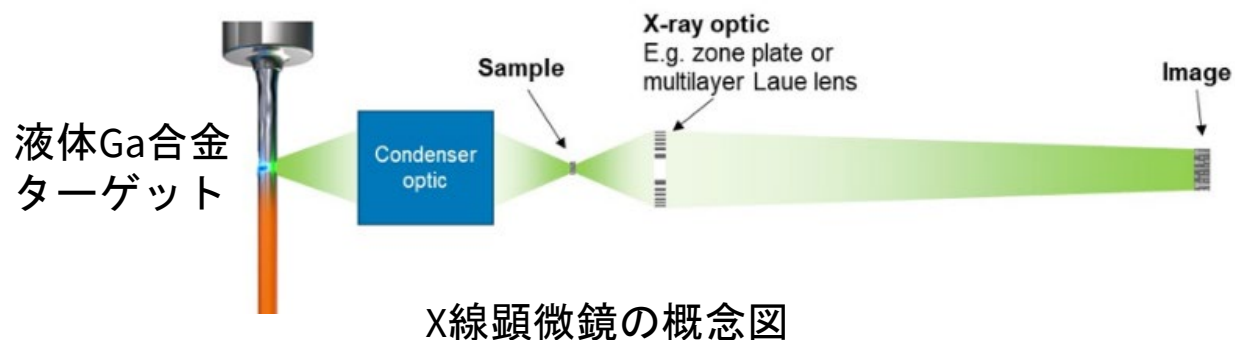
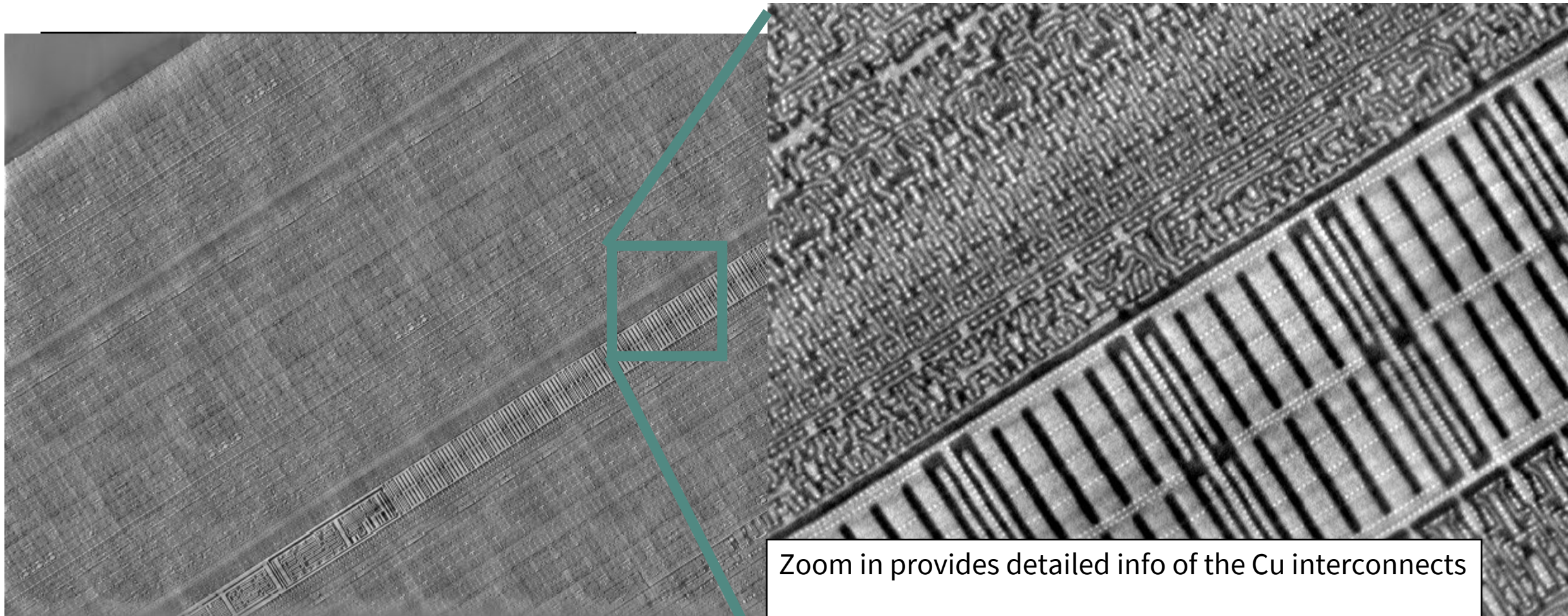


Image courtesy of Carsten Gundlach of Imaging at DTU, Denmark



X線CTによる90 nm ノード Cu配線の観察 (18x7 stitched overlapping tomographies)



Xray micrograph of one of the reconstructed layers

Zoom in provides detailed info of the Cu interconnects

Note that Xray tomography provides 3D information on all layers. This illustrates a 2D representation of one layer

パートナー企業*

ターンキーシステム販売企業



by VisiConsult


Battery inspection systems



Phase-contrast imaging systems




Nano CT systems




Nano CT systems




High pressure XRD systems




Single crystal X-ray diffraction systems (protein/macro molecule)




Single crystal X-ray diffraction systems (small & protein/macro molecule)



Single crystal X-ray diffraction systems (small molecule & powder)



Small angle X-ray scattering (SAXS) systems



Small angle X-ray scattering (SAXS) systems



Electron diffraction systems



HAXPES systems

カスタムシステム販売企業



Custom X-ray analytical systems (worldwide)



Custom X-ray imaging systems (North America)



Custom X-ray analytical systems (China)



Custom X-ray systems (Taiwan)

X線源販単体 販売代理店



North America



China



Korea



Japan

*公開可能な企業のみ掲載

デモ測定をご利用ください！

(1) サンプルをお送りください。

弊社で測定して結果をお送りいたします。

(2) 弊社へお越しください。

サンプルや普段お使いの検出器などをお持ちください。測定をお手伝いいたします。

お問い合わせはこちらへ
shiho.tanaka@excillum.com

ナノ CT



2D ナノ測定



MetalJet 高速 CT

